

**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**
**Applications**

- Bluetooth™ wireless technology (Class 1)
- USB dongles, PCMCIA, flash cards, Access Points
- Enhanced data rate

**Features**

- Integrated input and inter-stage match
- +25 dBm GFSK Output Power
- +19.5 dBm 8DPSK Output Power
- Low current: 110 mA typical @  $P_{OUT} = +20$  dBm
- Ultra low quiescent current: 28 mA
- Digital Enable for direct interface to standard CMOS processors
- Mode-control for easy switching between standard and EDR modes
- Lead Free and RoHS Compliant
- Ultra thin package: 0.5 mm
- 3.3 V single supply operation

**Product Description**

A monolithic, high-efficiency, silicon-germanium power amplifier IC, the SE2425U is designed for 2.4 GHz wireless applications, including Bluetooth™ Class 1 basic rate and enhanced data rate applications. It delivers +25 dBm output power in standard rate GFSK mode and +19.5 dBm output power in enhanced rate 8DPSK.

The SE2425U provides a digital mode control input for boosting the linear performance for enhanced data rate applications.

The SE2425U operates at 3.3 V DC with a peak efficiency of 43 % in basic rate and 21 % in enhanced rate mode. The internal bias management allows the part to only draw 28 mA in Class 2 output power levels.

Output match integrates the high Q inductors to reduce component count and bill of materials. It uses two external capacitors to allow for varying loads, such as switches and filters, in different applications.

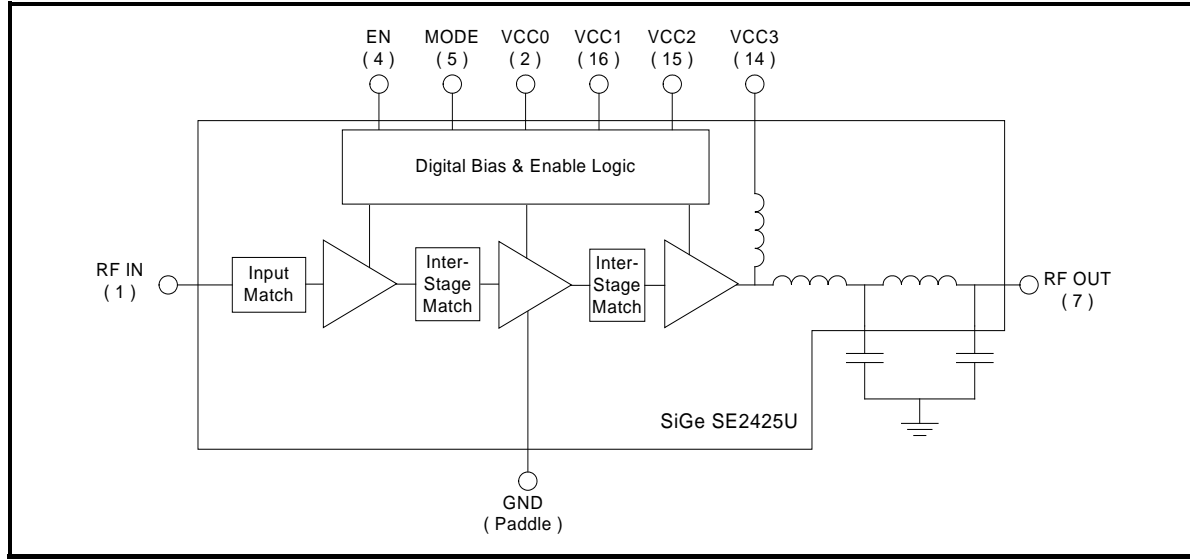
The silicon/silicon-germanium structure of the SE2425U, and its exposed die-pad package, soldered to the system PCB, provide high thermal conductivity and a subsequently low junction temperature. This device is capable of operating at a duty cycle of 100 percent.

**Ordering Information**

Type	Package	Remark
SE2425U	3 x 3 x 0.5 mm QFN	Sample
SE2425U-R	3 x 3 x 0.5 mm QFN	Tape & Reel
SE2425U-EK1	N/A	Evaluation Kit

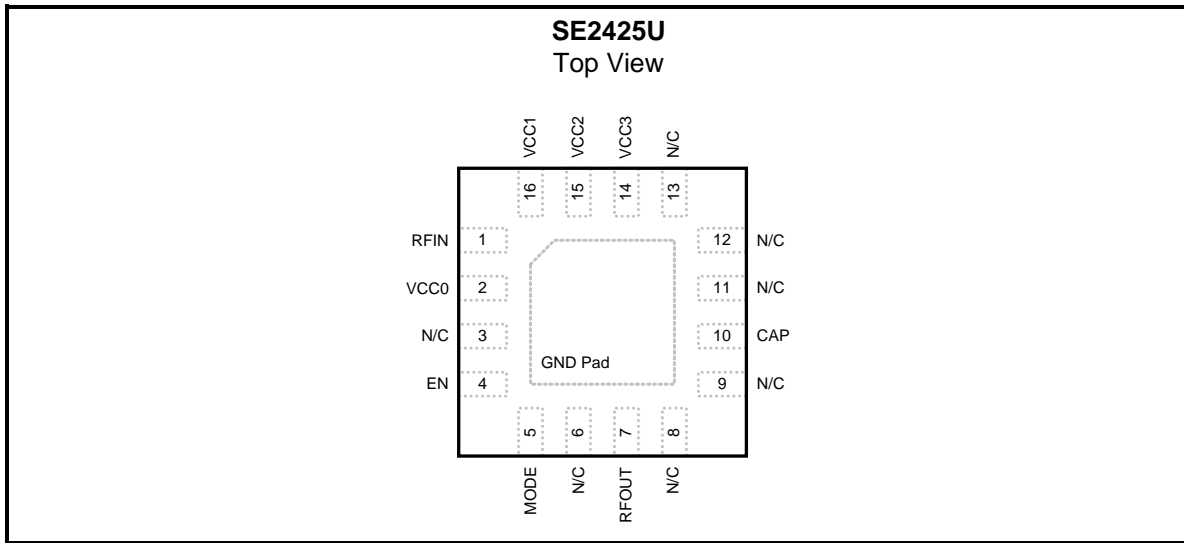
**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**

**Functional Block Diagram**



**Figure 1: SE2425U Block Diagram**

**Pin-Out Diagram**



**Figure 2: SE2425U Pin-Out**

**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**
**Pin Out Description**

Pin No.	Name	Description
1	RF <sub>IN</sub>	Power amplifier RF input, DC blocking is required
2	V <sub>CC0</sub>	Bias Power Supply
3	N/C	Do Not Connect
4	EN	PA Enable
5	MODE	Mode switch
6	N/C	Do Not Connect
7	RF <sub>OUT</sub>	RF output Note: Requires external DC blocking and optional shunt capacitor (typically 0p75 0402)
8	N/C	Do Not Connect
9	N/C	Do Not Connect
10	CAP	Matching capacitor (typically 1p3 0402)
11	N/C	Do Not Connect
12	N/C	Do Not Connect
13	N/C	Do Not Connect
14	V <sub>CC3</sub>	Stage 3 collector supply voltage
15	V <sub>CC2</sub>	Stage 2 collector supply voltage
16	V <sub>CC1</sub>	Stage 1 collector supply voltage
GND Pad	GND	Heat slug Ground Pad

**Absolute Maximum Ratings**

These are stress ratings only. Exposure to stresses beyond these maximum ratings may cause permanent damage to, or affect the reliability of the device. Avoid operating the device outside the recommended operating conditions defined below. This device is ESD sensitive. Handling and assembly of this device should be at ESD protected workstations.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	-0.3	+4.2	V
V <sub>LOGIC</sub>	Logic Voltage	-0.3	V <sub>CC</sub>	V
IN	RF Input Power	-	0	dBm
T <sub>C</sub>	Case Temperature Range	-40	+85	°C
T <sub>STG</sub>	Storage Temperature Range	-40	+150	°C
T <sub>J</sub>	Maximum Junction Temperature	-	+150	°C

**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**
**DC Electrical Characteristics**

Conditions:  $V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ ,  $T_C = 25\text{ }^{\circ}\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks Solutions' SE2425U-EV1 evaluation board unless otherwise noted.

Symbol	Parameter	Min.	Typ.	Max.	Unit
$V_{CC}$	Supply Voltage	2.7	3.3	3.6	V
$I_{CC}$	Supply Current $V_{MODE} = \text{Low}$ , $P_{OUT} = 20\text{ dBm}$	-	110	-	mA
	Supply Current $V_{MODE} = \text{Low}$ , No RF	-	28	-	mA
	Supply Current $V_{MODE} = \text{High}$ , No RF	-	81	-	mA
	Supply Current $V_{MODE} = \text{High}$ , $P_{OUT} = 19.5\text{ dBm}$	-	123	-	mA
$I_{EN}$	Current sunk by EN pin (logic high)	-	-	1	$\mu\text{A}$
$I_{MODE}$	Current sunk by MODE pin (logic high)	-	-	1	$\mu\text{A}$
$V_{LOGIC}$	Logic High Voltage ( $V_{LOGIC} \leq V_{CC}$ )	2.0	2.8	3.6	V
	Logic Low Voltage	0	-	0.8	V
$I_{stdby}$	Leakage Current when $V_{EN} = V_{MODE} = 0\text{ V}$ , No RF	-	1	10	$\mu\text{A}$

**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**
**AC Electrical Characteristics**

Conditions:  $V_{EN} = V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ ,  $V_{MODE} = \text{Low}$ ,  $P_{IN} = -6\text{ dBm}$ ,  $T_C = 25\text{ }^{\circ}\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks Solutions' SE2425U-EV1 evaluation board, unless otherwise noted

Standard Rate Mode					
Symbol	Parameter	Min.	Typ.	Max.	Unit
$f_{L-U}$	Frequency Range	2400	-	2500	MHz
$P_{OUT\_MAX}$	GFSK Maximum Output Power ( $P_{IN} = 0\text{ dBm}$ )	-	25	-	dBm
	EDR Maximum Output Power (Meets ACPR1/2 specification)	-	17.5	-	dBm
$\Delta P_{temp}$	Output Power variation over temperature ( $-40\text{ }^{\circ}\text{C} < T_A < +85\text{ }^{\circ}\text{C}$ )	-	0.5	-	dB
G	Gain @ $P_{IN} = -25\text{ dBm}$ Gain @ $P_{IN} = -6\text{ dBm}$	-	29.5 28.2	-	dB
$G_{VAR}$	Gain Variation over band (2400-2500 MHz)	-	0.3	1.0	dB
2f	Harmonics	-	-39	-	dBc
3f		-	-45	-	
$IS_{11I}$	-	10	-	-	dB
$IS_{21I\_OFF}$	Isolation in "OFF" State, $V_{EN} = 0\text{ V}$	-	36	-	dB
$IS_{12I}$	Reverse Isolation	-	42	-	dB
STAB	Stability ( $P_{IN} = -6\text{ dBm}$ , Load VSWR = 4:1)	All non-harmonically related outputs less than -50 dBc			

Conditions:  $V_{EN} = V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ ,  $V_{MODE} = \text{High}$ ,  $T_C = 25\text{ }^{\circ}\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks Solutions' SE2425U-EV1 evaluation board, unless otherwise noted.

Enhanced Rate Mode					
Symbol	Parameter	Min.	Typ.	Max.	Unit
$P_{OUT\_MAX}$	Output Power (Meets ACPR1/2 specification)	-	19.5	-	dBm
$\Delta P_{temp}$	Output Power variation over temperature ( $-40\text{ }^{\circ}\text{C} < T_A < +85\text{ }^{\circ}\text{C}$ ) for $P_{IN} = -15\text{ dBm}$	-	1.5	-	dB
G	Gain @ $P_{IN} = -25\text{ dBm}$	-	30.5	-	dB
$G_{VAR}$	Gain Variation over band, $P_{IN} = -25\text{ dBm}$	-	0.25	1.5	dB
ACPR1	2 Mbps, $\pi/4$ -DQPSK, $F_C \pm 2\text{ MHz}$ , BW = 1 MHz	-	-	-20	dBm
	3 Mbps, 8DPSK, $F_C \pm 2\text{ MHz}$ , BW = 1 MHz	-	-	-20	dBm
ACPR2	2 Mbps, $\pi/4$ -DQPSK, $F_C \pm 3\text{ MHz}$ , BW = 1 MHz	-	-	-40	dBm
	3 Mbps, 8DPSK, $F_C \pm 3\text{ MHz}$ , BW = 1 MHz	-	-	-40	dBm

## DATA SHEET

### SE2425U : 2.4 GHz Bluetooth Power Amplifier IC

## Typical Performance Characteristics

### Low Mode

Test Conditions:  $V_{EN} = V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ , MODE = Low,  $T_c = 25\text{ }^{\circ}\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks' SE2425U-EV1 evaluation board otherwise noted

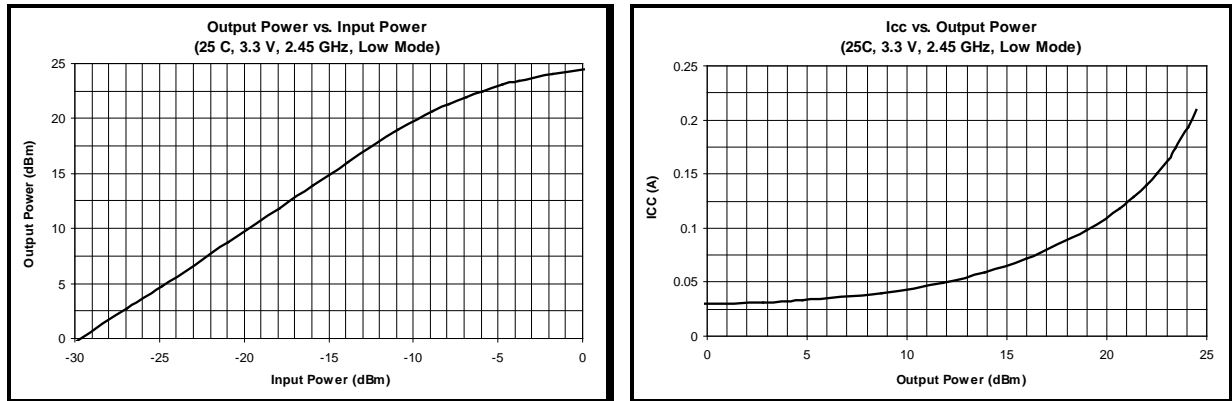


Figure 3: Typical Performance Data in Low Mode (a) Output Power vs. Input Power, (b) Current vs. Output Power

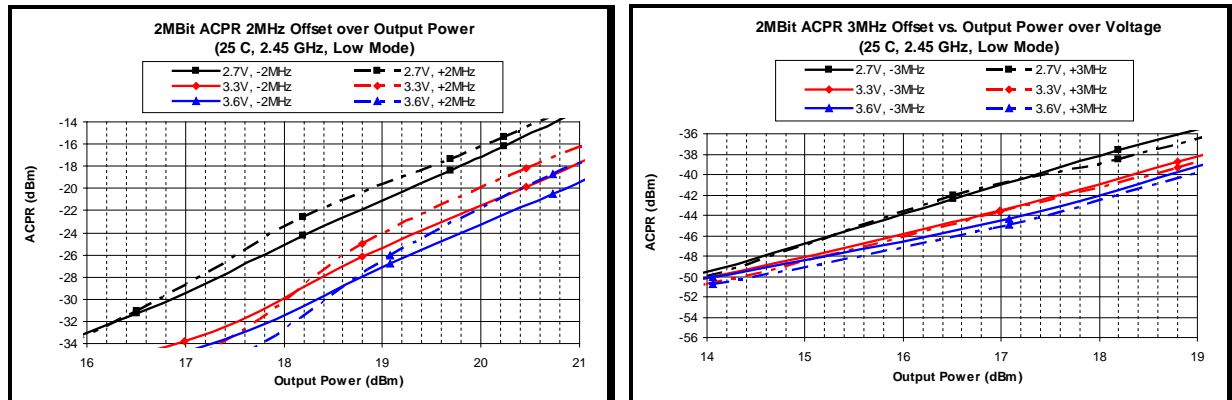


Figure 4: Typical 2 Mbps Enhanced Data Rate (EDR) Performance Data in Low Mode (a) ACPR @ 2 MHz Offset vs. Output Power over Voltage (b) ACPR @ 3 MHz Offset vs. Output Power over voltage

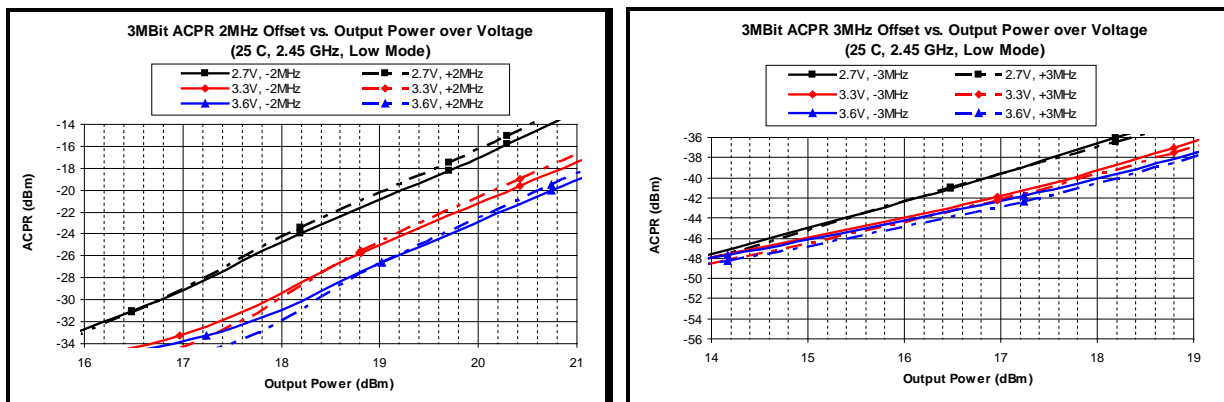
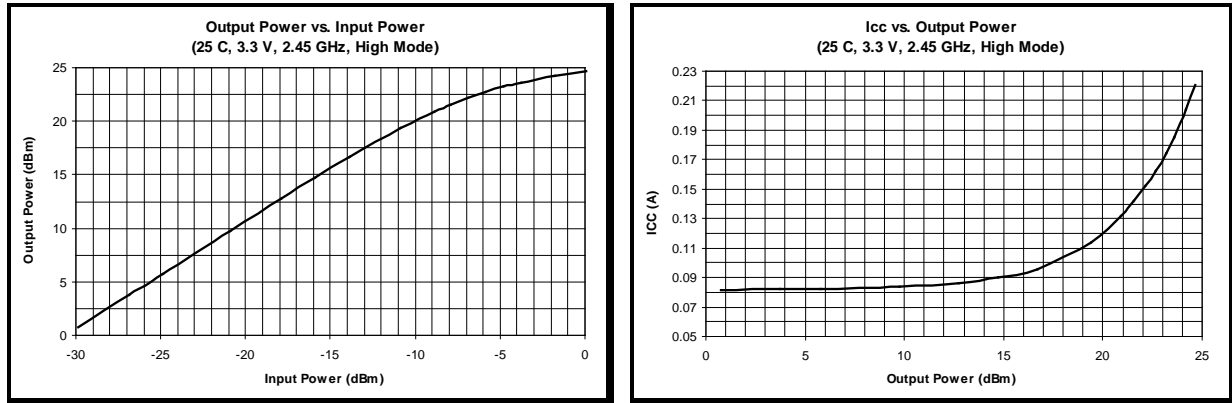


Figure 5: Typical 3 Mbps Enhanced Data Rate (EDR) Performance Data in Low Mode (a) ACPR @ 2 MHz Offset vs. Output Power over Voltage (b) ACPR @ 3 MHz Offset vs. Output Power over voltage

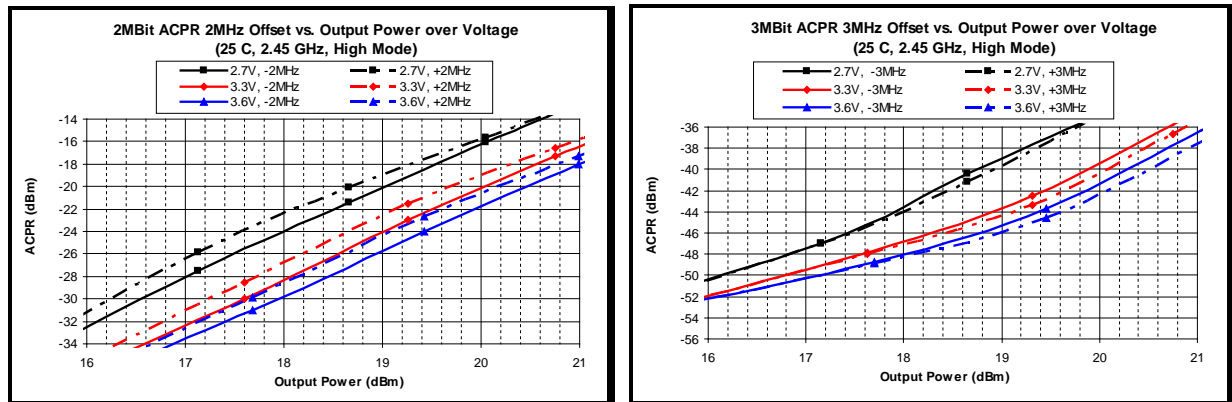
**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**

**High Mode**

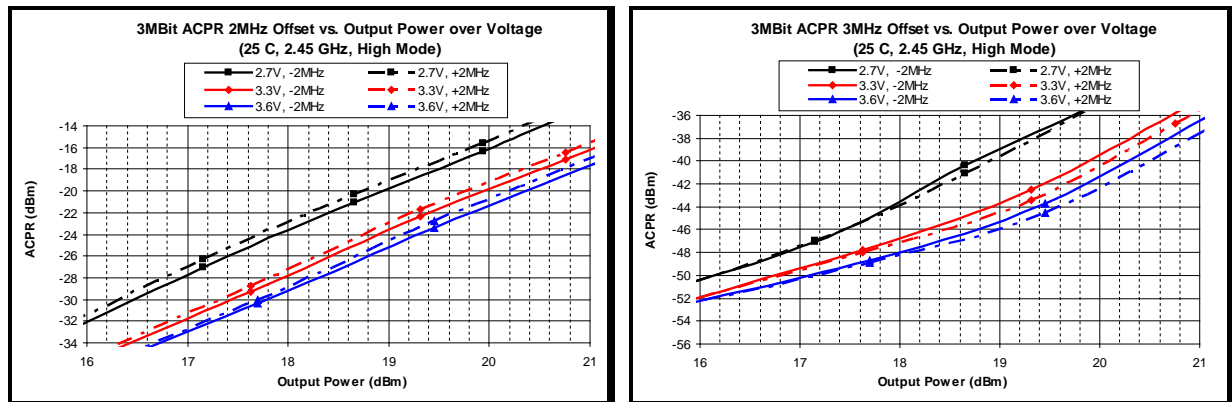
Test Conditions:  $V_{EN} = V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ , MODE = High,  $T_c = 25\text{ }^\circ\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks' SE2425U-EV1 evaluation board otherwise noted



**Figure 6: Typical Performance Data in High Mode (a) Output Power vs. Input Power , (b) Current vs. Output Power**



**Figure 7: Typical 2 Mbps Enhanced Data Rate (EDR) Performance Data in High Mode (a) ACPR @ 2 MHz Offset vs. Output Power over Voltage (b) ACPR @ 3 MHz Offset vs. Output Power over Voltage**



**Figure 8: Typical 3 Mbps Enhanced Data Rate (EDR) Performance Data in High Mode (a) ACPR @ 2 MHz Offset vs. Output Power over Voltage (b) ACPR @ 3 MHz Offset vs. Output Power over Voltage**

**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**

**Harmonic Performance**

Test Conditions:  $V_{EN} = V_{CC0} = V_{CC1} = V_{CC2} = V_{CC3} = 3.3\text{ V}$ ,  $T_c = 25\text{ }^{\circ}\text{C}$ ,  $f = 2.45\text{ GHz}$ , as measured on Skyworks' SE2425U-EV1 evaluation board otherwise noted

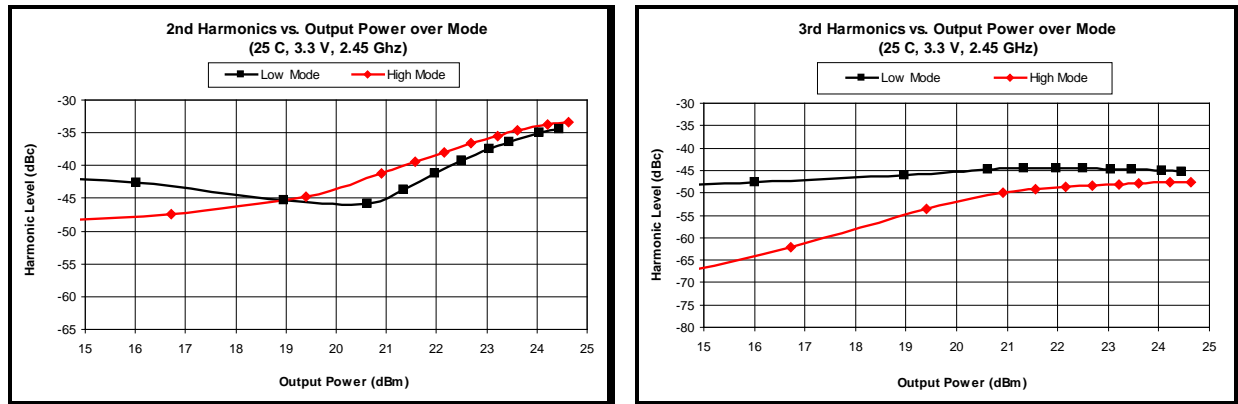


Figure 9: Typical Harmonic Performance Data in Low and High Mode (a) 2<sup>nd</sup> Harmonic Performance in Low and High Mode (b) 3<sup>rd</sup> Harmonic Performance in Low and High Mode

**Branding Information**

Figure 10 shows the SE2425U branding.

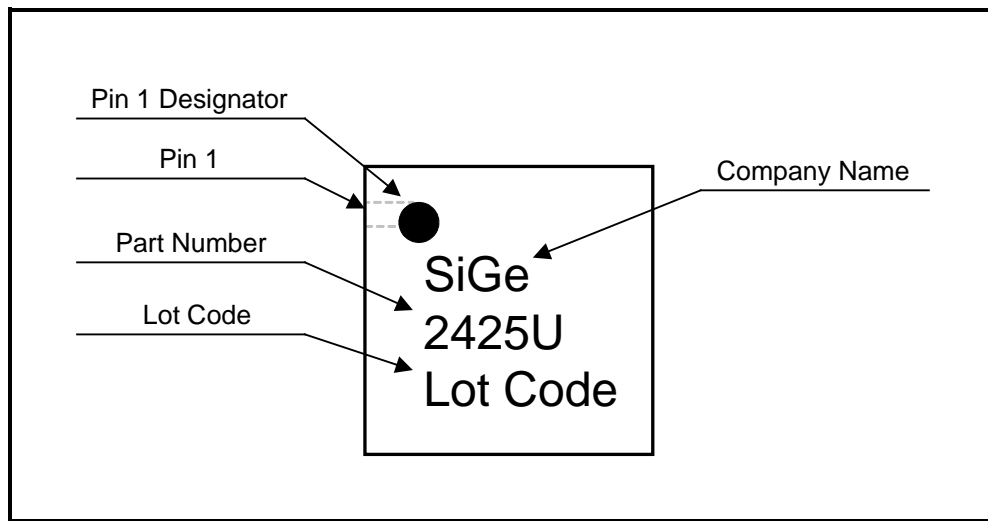


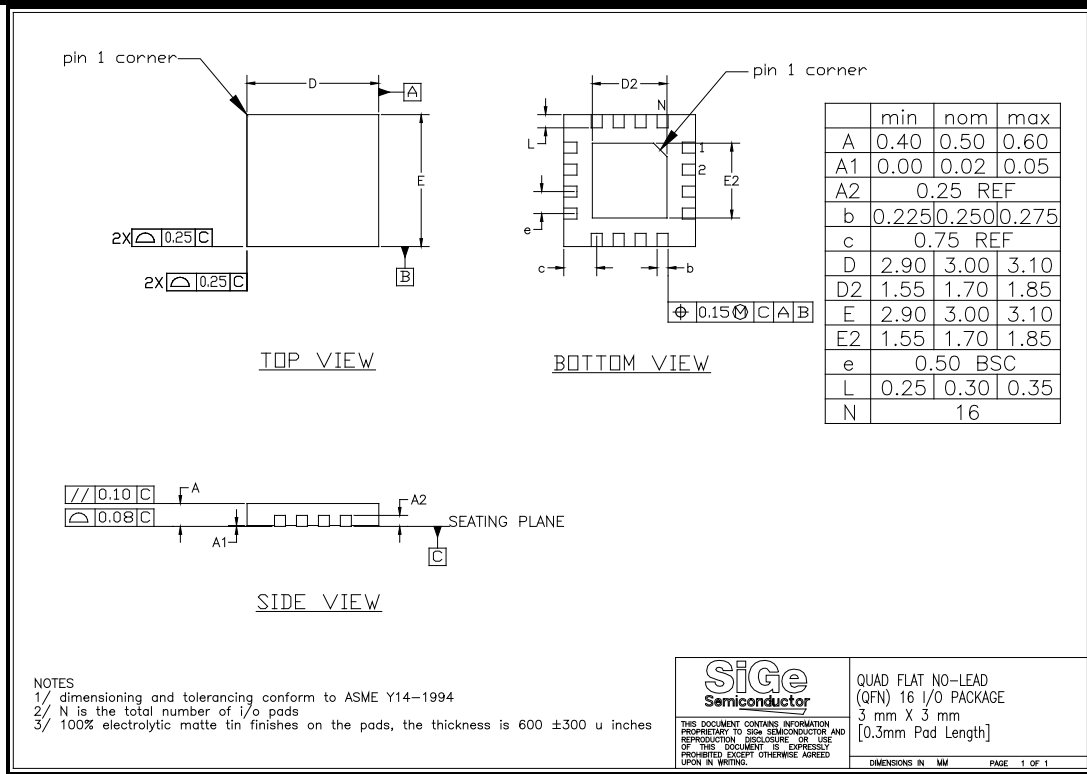
Figure 10: SE2425U Branding Information

**Package Information**

This package is lead free.



**DATA SHEET**  
**SE2425U : 2.4 GHz Bluetooth Power Amplifier IC**



**Figure 11: SE2425U Package Drawing**

Copyright © 2012 Skyworks Solutions, Inc. All Rights Reserved.

Information in this document is provided in connection with Skyworks Solutions, Inc. ("Skyworks") products or services. These materials, including the information contained herein, are provided by Skyworks as a service to its customers and may be used for informational purposes only by the customer. Skyworks assumes no responsibility for errors or omissions in these materials or the information contained herein. Skyworks may change its documentation, products, services, specifications or product descriptions at any time, without notice. Skyworks makes no commitment to update the materials or information and shall have no responsibility whatsoever for conflicts, incompatibilities, or other difficulties arising from any future changes.

No license, whether express, implied, by estoppel or otherwise, is granted to any intellectual property rights by this document. Skyworks assumes no liability for any materials, products or information provided hereunder, including the sale, distribution, reproduction or use of Skyworks products, information or materials, except as may be provided in Skyworks Terms and Conditions of Sale.

THE MATERIALS, PRODUCTS AND INFORMATION ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, WHETHER EXPRESS, IMPLIED, STATUTORY, OR OTHERWISE, INCLUDING FITNESS FOR A PARTICULAR PURPOSE OR USE, MERCHANTABILITY, PERFORMANCE, QUALITY OR NON-INFRINGEMENT OF ANY INTELLECTUAL PROPERTY RIGHT; ALL SUCH WARRANTIES ARE HEREBY EXPRESSLY DISCLAIMED. SKYWORKS DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. SKYWORKS SHALL NOT BE LIABLE FOR ANY DAMAGES, INCLUDING BUT NOT LIMITED TO ANY SPECIAL, INDIRECT, INCIDENTAL, STATUTORY, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS THAT MAY RESULT FROM THE USE OF THE MATERIALS OR INFORMATION, WHETHER OR NOT THE RECIPIENT OF MATERIALS HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

Skyworks products are not intended for use in medical, lifesaving or life-sustaining applications, or other equipment in which the failure of the Skyworks products could lead to personal injury, death, physical or environmental damage. Skyworks customers using or selling Skyworks products for use in such applications do so at their own risk and agree to fully indemnify Skyworks for any damages resulting from such improper use or sale.

Customers are responsible for their products and applications using Skyworks products, which may deviate from published specifications as a result of design defects, errors, or operation of products outside of published parameters or design specifications. Customers should include design and operating safeguards to minimize these and other risks. Skyworks assumes no liability for applications assistance, customer product design, or damage to any equipment resulting from the use of Skyworks products outside of stated published specifications or parameters.

Skyworks, the Skyworks symbol, and "Breakthrough Simplicity" are trademarks or registered trademarks of Skyworks Solutions, Inc., in the United States and other countries. Third-party brands and names are for identification purposes only, and are the property of their respective owners. Additional information, including relevant terms and conditions, posted at [www.skyworksin.com](http://www.skyworksin.com), are incorporated by reference.